

AN-1969 LM3424 Boost Evaluation Board

1 Introduction

This evaluation board showcases the LM3424 NFET controller used with a boost current regulator. It is designed to drive 9 to 12 LEDs at a maximum average LED current of 1A from a DC input voltage of 10 to 26V.

The evaluation board showcases many of the LM3424 features including thermal foldback, analog dimming, external switching frequency synchronization, and high frequency PWM dimming, among others. There are many external connection points to facilitate the full evaluation of the LM3424 device including inputs, outputs and test points. Refer to [Table](#page-1-0) 1 for a summary of the connectors and test points.

The boost circuit can be easily redesigned for different specifications by changing only a few components (see [Alternate](#page-13-0) Designs). Note that design modifications can change the system efficiency for better or worse.

This application note is designed to be used in conjunction with the LM3424 Constant Current N-Channel Controller with Thermal Foldback for Driving LEDs ([SNVS603\)](http://www.ti.com/lit/pdf/SNVS603) data sheet as a reference for the LM3424 boost evaluation board and for a comprehensive explanation of the device, design procedures, and application information.

2 Key Features

- Input: 10V to 26V
- Output: 9 to 12 LEDs at 1A
- Thermal Foldback / Analog Dimming
- PWM Dimming up to 30 kHz
- External Synchronization > 360 kHz
- Input Under-voltage and Output Over-voltage Protection

Figure 1. Efficiency with 6 Series LEDS AT 1A

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3 External Connection Descriptions

Table 1. Connectors and Test Points

www.ti.com Schematic Schematic Schematic Schematic Schematic Schematic Schematic Schematic Schematic Schematic

4 Schematic

5 LM3424 Pin Descriptions

Bill of Materials

PCB Layout www.ti.com

7 PCB Layout

Figure 2. Top Layer

Figure 3. Bottom Layer

8 Design Procedure

8.1 Specifications

 $N = 6$ $V_{LED} = 3.5V$ $r_{LED} = 325$ m Ω $V_{IN} = 24V$ $V_{IN-MIN} = 10V$ $V_{IN-MAX} = 70V$ $f_{SW} = 500$ kHz $V_{SNS} = 100$ mV $I_{LED} = 1A$ $\Delta i_{L-PP} = 700$ mA Δi _{LED-PP} = 12 mA $\Delta v_{\text{IN-PP}} = 100 \text{ mV}$ $I_{LIM} = 6A$ $V_{TURN-ON} = 10V$ $V_{HYS} = 3V$ $V_{TURN-OFF} = 40V$ $V_{HYSO} = 10V$ $T_{BK} = 70^{\circ}C$ T_{END} = 120 $^{\circ}$ C $t_{TSU} = 30$ ms

8.2 Operating Point

 $V_{\text{O}} = N \times V_{\text{LED}} = 9 \times 3.5V = 31.5V$ Solve for V_{O} and r_{D} : (1)

(2)

Solve for D, D', D_{MAX} , and D_{MIN} :

$$
r_{D} = N \times r_{LED} = 9 \times 325 \text{ m}\Omega = 2.925 \Omega
$$
\n
$$
\text{For D, D', D}_{MAX}, \text{ and D}_{MIN}:
$$
\n
$$
D = \frac{V_{O} - V_{IN}}{V_{O}} = \frac{31.5V - 24V}{31.5V} = 0.238
$$
\n
$$
\tag{3}
$$

$$
D' = 1 - D = 1 - 0.238 = 0.762
$$

$$
D' = 1 - D = 1 - 0.238 = 0.762
$$
\n
$$
D_{\text{MIN}} = \frac{V_O - V_{\text{IN-MAX}}}{V_O} = \frac{31.5V - 26V}{31.5V} = 0.175
$$
\n(5)

$$
D_{MAX} = \frac{V_O - V_{IN-MIN}}{V_O} = \frac{31.5V - 10V}{31.5V} = 0.683
$$
 (6)

8.3 Switching Frequency

Solve for R_T :

$$
R10 = \frac{1 + 1.95e^{-8} \times f_{SW}}{1.40e^{-10} \times f_{SW}} = \frac{1 + 1.95e^{-8} \times 360 \text{ kHz}}{1.40e^{-10} \times 360 \text{ kHz}} = 19.99 \text{ k}\Omega
$$

(7)

(4)

The closest standard resistor is 14.3 kΩ therefore f_{sw} is:

$$
f_{SW} = \frac{1}{1.40e^{-10} \times R10 - 1.95e^{-8}}
$$

$$
f_{SW} = \frac{1}{1.40e^{-10} \times 20.0 \text{ k}\Omega - 1.95e^{-8}} = 360 \text{ kHz}
$$
 (8)

The chosen component from step 2 is:

$$
R10 = 20 \text{ k}\Omega
$$
 (9)

8.4 Average LED Current

Solve for R_{SNS} :

$$
R9 = \frac{V_{\text{SNS}}}{I_{\text{LED}}} = \frac{100 \text{ mV}}{1 \text{A}} = 0.1 \Omega
$$
\n(10)

Assume R_{CSH} = 12.4 k Ω and solve for R_{HSP} :

$$
R8 = \frac{I_{LED} \times R1 \times R9}{1.24 \text{V}} = \frac{1 \text{A} \times 1.24 \text{ k}\Omega \times 0.1 \Omega}{1.24 \text{V}} = 1.0 \text{ k}\Omega
$$
\n(11)

The closest standard resistor for R_{SNS} is actually 0.1Ω and for R_{HSP} is actually 1 kΩ therefore I_{LED} is:

$$
I_{LED} = \frac{1.24V \times R8}{R9 \times R1} = \frac{1.24V \times 1.0 \text{ k}\Omega}{0.1 \Omega \times 1.24 \text{ k}\Omega} = 1.0 \text{A}
$$
\n(12)

The chosen components from step 3 are:

$$
R9 = 0.1\Omega
$$

R1 = 12.4 k Ω
R8 = R7 = 1 k Ω (13)

8.5 Thermal Foldback

Using a standard 100k NTC thermistor (connected to pins 4 and ll), find the resistances corresponding to ${\sf T}_{\sf BK}$ and ${\sf T}_{\sf END}$ (${\sf R}_{\sf NTC-BK}$ = 243 kΩ and ${\sf R}_{\sf NTC-END}$ = 71.5 kΩ) from the manufacturer's datasheet. Assuming ${\sf R}_{\sf REF1}$ = R_{REF2} = 49.9 kΩ, then R_{BIAS} = R_{NTC-BK} = 243 kΩ.

Solve for R_{GAIN} :

$$
R_{\text{GAIN}} = \frac{\left(\frac{R_{\text{REF1}}}{R_{\text{REF1}} + R_{\text{REF2}}}-\frac{R_{\text{NTC-END}}}{R_{\text{NTC-END}} + R_{\text{BIAS}}}\right) \times 2.45V}{I_{\text{CSH}}}
$$

$$
R_{\text{GAIN}} = \frac{\left(\frac{1}{2} - \frac{71.5 \text{ k}\Omega}{71.5 \text{ k}\Omega + 243 \text{ k}\Omega}\right) \times 2.45V}{100 \text{ }\mu\text{A}} = 6.68 \text{ k}\Omega
$$

The chosen components from step 4 are:

$$
R_{\text{GAIN}} = 6.81 \text{ k}\Omega
$$

\n
$$
R_{\text{BIAS}} = 243 \text{ k}\Omega
$$

\n
$$
R_{\text{REF1}} = R_{\text{REF2}} = 49.9 \text{ k}\Omega
$$

8.6 Inductor Ripple Current

Solve for L1:

$$
L1 = \frac{V_{IN} \times D}{\Delta i_{L-PP} \times f_{SW}} = \frac{24V \times 0.238}{500 \text{ mA} \times 360 \text{ kHz}} = 31.7 \text{ }\mu\text{H}
$$

The closest standard inductor is 33 μ H therefore Δi_{L-PP} is:

 (14)

(15)

(16)

(19)

(24)

(26)

$$
\Delta i_{L-PP} = \frac{V_{IN} \times D}{L1 \times f_{SW}} = \frac{24V \times 0.238}{33 \mu H \times 360 \text{ kHz}} = 481 \text{ mA}
$$
\n(17)

Determine minimum allowable RMS current rating:

$$
I_{L-RMS} = \frac{I_{LED}}{D'} \times \sqrt{1 + \frac{1}{12} \times \left(\frac{\Delta I_{L-PP} \times D'}{I_{LED}}\right)^2}
$$

\n
$$
I_{L-RMS} = \frac{1A}{0.762} \times \sqrt{1 + \frac{1}{12} \times \left(\frac{481 \text{ mA} \times 0.762}{1A}\right)^2} = 1.32A
$$
 (18)

The chosen component from step 5 is:

$$
L1 = 33 \, \mu H
$$

8.7 Output Capacitance

Solve for C_0 :

$$
C_O = \frac{I_{LED} \times D}{r_D \times \Delta I_{LED-PP} \times f_{SW}}
$$

$$
L1 = 33 \mu H
$$
\n
$$
Out Capacitance
$$
\n
$$
For CO:
$$
\n
$$
CO = \frac{I_{LED} \times D}{I_D \times \Delta I_{LED-PP} \times f_{SW}}
$$
\n
$$
CO = \frac{1A \times 0.238}{2.925 \Omega \times 6 \text{ mA} \times 360 \text{ kHz}} = 38 \mu F
$$
\n(20)

The closest capacitance totals 40 μ F therefore $\Delta i_{LED\text{-PP}}$ is:

$$
\Delta i_{LED\text{-}PP} = \frac{I_{LED} \times D}{r_D \times C_O \times f_{SW}}
$$

$$
\Delta i_{LED-PP} = \frac{1A \times 0.238}{2.925 \Omega \times 40 \mu F \times 360 \text{ kHz}} = 5.7 \text{ mA}
$$
\n(21)

Determine minimum allowable RMS current rating:

$$
I_{\text{CO-RMS}} = I_{\text{LED}} \times \sqrt{\frac{D_{\text{MAX}}}{1 - D_{\text{MAX}}}} = 1 \text{A} \times \sqrt{\frac{0.683}{1 - 0.683}} = 1.47 \text{A}
$$
\n(22)

The chosen components from step 6 are:

$$
C4 = C6 = C17 = C19 = 10 \, \mu\text{F}
$$
\n⁽²³⁾

8.8 Peak Current Limit

Solve for R_{LIM} :

$$
R6 = \frac{245 \text{ mV}}{I_{LIM}} = \frac{245 \text{ mV}}{6A} = 0.041 \Omega
$$

lossest standard resistor is 0.04 Ω therefore I_{LIM} is:

$$
245 \text{ mV} = 245 \text{ mV}
$$

The closest standard resistor is 0.04 Ω therefore $I_{\text{\tiny{LIM}}}$ is:

$$
I_{\text{LIM}} = \frac{245 \text{ mV}}{R6} = \frac{245 \text{ mV}}{0.04 \Omega} = 6.13 \text{A}
$$
 (25)

The chosen component from step 7 is:

 $R6 = 0.04\Omega$

8.9 Slope Compensation

Solve for R_{SLP} :

8.11 Input Capacitance

Solve for the minimum C_{IN} :

$$
C_{IN} = \frac{\Delta i_{L-PP}}{8 \times \Delta v_{IN-PP} \times f_{SW}} = \frac{481 \text{ mA}}{8 \times 50 \text{ mV} \times 360 \text{ kHz}} = 3.4 \text{ }\mu\text{F}
$$

(37)

To minimize power supply interaction a 200% larger capacitance of approximately 20 µF is used, therefore the actual $\Delta v_{\text{IN-PP}}$ is much lower. Since high voltage ceramic capacitor selection is limited, four 4.7 µF X7R capacitors are chosen.

www.ti.com **Design Procedure**

Determine minimum allowable RMS current rating:

$$
I_{IN-RMS} = \frac{\Delta I_{L-PP}}{\sqrt{12}} = \frac{481 \text{ mA}}{\sqrt{12}} = 139 \text{ mA}
$$
\n(38)

The chosen components from step 10 are:

$$
C2 = C3 = C16 = C18 = 6.8 \text{ }\mu\text{F}
$$
\n(39)

8.12 NFET

 $C2 = C3 = C16 = C18 = 6.8 \mu F$

T

mine minimum Q1 voltage

V_{T-MAX} = V_O = 31.5V Determine minimum Q1 voltage rating and current rating:

$$
I_{T-MAX} = \frac{0.683}{1 - 0.683} \times 1A = 2.2A
$$
 (41)

 $I_{T\text{-MAX}} = \frac{0.683}{1 - 0.683} \times 1 \text{A} = 2.2 \text{A}$

V NFET is chosen with a
 $I_{T\text{-RMS}} = \frac{I_{LED}}{D'} \times \sqrt{D} = \frac{1 \text{A}}{0.762} \times \sqrt{D}$ A 100V NFET is chosen with a current rating of 32A due to the low R_{DS-ON} = 50 mΩ. Determine I_{T-RMS} and P_T :

$$
I_{T-RMS} = \frac{I_{LED}}{D'} \times \sqrt{D} = \frac{1A}{0.762} \times \sqrt{0.238} = 640 \text{ mA}
$$
\n
$$
P_T = I_{T-RMS}^2 \times R_{DSON} = 640 \text{ mA}^2 \times 50 \text{ m}\Omega = 20 \text{ mW}
$$
\n(42)

$$
P_T = I_{T-RMS}^2 \times R_{DSON} = 640 \text{ mA}^2 \times 50 \text{ m}\Omega = 20 \text{ mW}
$$
\nchosen component from step 11 is:

\n
$$
Q1 \rightarrow 32A, 100V, DPAK
$$
\nHe:

\nminem minimum D1 voltage rating and current rating:

\n
$$
V_{RD-MAX} = V_0 = 31.5V
$$
\n(45)

The chosen component from step 11 is:

 \overline{a}

8.13 Diode

Determine minimum D1 voltage rating and current rating:

$$
I_{D-MAX} = I_{LED} = 1A \tag{46}
$$

 $I_{\rm D-MAX}$ = I_{LED} = 1A
/ diode is chosen with a curi
P_D = I_D x V_{FD} = 1A x 600 mV = 600 mW A 100V diode is chosen with a current rating of 12A and V_D = 600 mV. Determine P_D:

The chosen component from step 12 is:

$$
PD = ID x VFD = 1A x 600 mV = 600 mW
$$
\n(47)\n
$$
100 \text{sech component from step 12 is:}
$$
\n
$$
D1 \rightarrow 12A, 100V, DPAK
$$
\n(48)

8.14 Input UVLO

Solve for R_{UV2} :

$$
R4 = \frac{R5 \times (V_{HYS} - 20 \mu A \times R13)}{20 \mu A \times (R5 + R13)}
$$

$$
R4 = \frac{1.43 \text{ k}\Omega \times (3V - 20 \mu A \times 10 \text{ k}\Omega)}{20 \mu A \times (1.43 \text{ k}\Omega + 10 \text{ k}\Omega)} = 17.5 \text{ k}\Omega
$$
(49)

The closest standard resistor is 150 k Ω therefore V_{HYS} is:

$$
V_{HYS} = \frac{20 \mu A \times R4 \times (R5 + R13)}{R5} + 20 \mu A \times R13
$$

$$
V_{HYS} = \frac{20 \mu A \times 17.4 \text{ k}\Omega \times (1.43 \text{ k}\Omega + 10 \text{ k}\Omega)}{1.43 \text{ k}\Omega}
$$

+ 20 \mu A \times 10 k\Omega = 2.98V (50)

Solve for R_{UV1} :

(40)

(44)

(47)

Design Procedure www.ti.com

8.15 Output OVLO

8.16 Soft-Start

$$
C_{SS} = \frac{(t_{TSU} - t_{SU-SS-BASE})}{20 \text{ k}\Omega} = \frac{(30 \text{ ms} - 10.5 \text{ ms})}{20 \text{ k}\Omega} = 975 \text{ nF}
$$

The chosen component from step 15 is:

$$
C_{SS} = 1 \mu F
$$

(62)

(61)

Typical Waveforms www.ti.com

9 Typical Waveforms

 T_A = +25°C, V_{IN} = 24V and V_O = 32V.

TP5 dim voltage (V_{DIM}) **LED current (ILED)**

10 Alternate Designs

Alternate designs with the LM3429 evaluation board are possible with very few changes to the existing hardware. The evaluation board FETs and diodes are already rated higher than necessary for design flexibility. The input UVLO, output OVP, input and output capacitance can remain the same for the designs shown below. These alternate designs can be evaluated by changing only R9, R10, and L1.

[Table](#page-14-0) 2 gives the main specifications for four different designs and the corresponding values for R9, R10, and L1. PWM dimming can be evaluated with any of these designs.

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